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THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Naoshi ADACHI et al.

Serial No.: 10/750,883

Filed: January 5, 2004

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Art Unit: 2812

Examiner: not yet assigned

Confirmation No.: 2099

For: Heat Treatment Jig for Semiconductor Substrate and Method of Heat Treating Semiconductor Substrate

SUBMISSION OF AMENDED DRAWINGS

Commissioner of Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

Enclosed is one sheet of replacement drawings to amend Figure 8 of the formal drawings filed January 5, 2004 with this application. The thickness is now correctly noted as **Ht**.

Entry is respectfully requested.

Respectfully submitted,
CLARK & BRODY

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Docket No.: 12054-0023

Date: May 24, 2004